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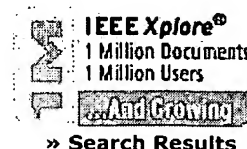
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### 1 Influence of plasma treatment and cleaning on vacuum wafer bonding

*Wei Bo Yu; Cher Ming Tan; Jun Wei; Shu Sheng Deng; Mui Ling Nai;*  
Electronics Packaging Technology, 2003 5th Conference (EPTC 2003) , 10-12 Dec. 2003

Pages:294 - 297

[\[Abstract\]](#)   [\[PDF Full-Text \(307 KB\)\]](#)   IEEE CNF

### 2 Plasma-assisted InP-to-Si low temperature wafer bonding

*Pasquariello, D.; Hjort, K.;*  
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Pages:118 - 131

[\[Abstract\]](#)   [\[PDF Full-Text \(443 KB\)\]](#)   IEEE JNL

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*Doll, A.; Goldschmidtboeing, F.; Woias, P.;*  
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*Choi, W.B.; Ju, C.M.; Ju, B.K.; Sung, M.Y.;*  
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**5 Material properties of plasma-thinned bonded SOI wafers**

*Feng, T.; Matloubian, M.; Mathur, D.P.; Mumola, P.B.; Gardopee, G.J.;*  
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**6 Surface quality of plasma-thinned bonded SOI wafers**

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*Suga, T.; Kim, T.H.; Howlader, M.M.R.;*  
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*En, W.G.; Malik, I.J.; Bryan, M.A.; Farrens, S.; Henley, F.J.; Cheung, N.W.; Chan, C.;*  
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**11 Low temperature direct bonding of nonhydrophilic surfaces**

*Watt, V.H.C.; Bower, R.W.;*  
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**14 Utility of using power spectral density to characterize SOI layer thickness uniformity**

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